

3.3 V / 5.0 V Ultra-Low Skew 1:4 Clock Fanout Buffer

Description

The NB3N551 is a low skew 1-to 4 clock fanout buffer, designed for clock distribution in mind. The NB3N551 specifically guarantees low output-to-output skew. Optimal design, layout and processing minimize skew within a device and from device to device.

The output enable (OE) pin three-states the outputs when low.

Features

- Input/Output Clock Frequency up to 180 MHz
- Low Skew Outputs (50 ps typical)
- Output goes to Three–State Mode via OE
- Operating Range: $V_{DD} = 3.0 \text{ V to } 5.5 \text{ V}$
- Ideal for Networking Clocks
- Packaged in 8-pin SOIC
- Industrial Temperature Range
- These are Pb–Free Devices

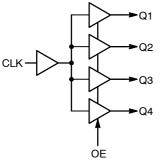
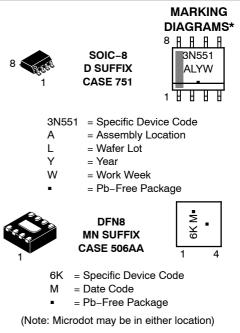


Figure 1. Block Diagram



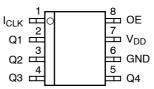
ON Semiconductor®

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*For additional marking information, refer to Application Note AND8002/D.

PIN CONNECTIONS



ORDERING INFORMATION

Device	Package	Shipping [†]
NB3N551DG	SOIC-8 (Pb-Free)	98 Units/Rail
NB3N551DR2G	SOIC-8 (Pb-Free)	2500/Tape & Reel
NB3N551MNR4G	DFN-8 (Pb-Free)	1000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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OE	Function	
0	Disable	
1	Enable	

Table 1. OE, Output Enable Function

PIN DESCRIPTION

Pin #	Name	Туре	Description	
1	I _{CLK}	(LV)CMOS/(LV)TTL Input	Clock Input. Internal pull-up resistor.	
2	Q1	(LV)CMOS/(LV)TTL Output	Clock Output 1	
3	Q2	(LV)CMOS/(LV)TTL Output	Clock Output 2	
4	Q3	(LV)CMOS/(LV)TTL Output	Clock Output 3	
5	Q4	(LV)CMOS/(LV)TTL Output	Clock Output 4	
6	GND	Power	Negative supply voltage; Connect to ground, 0 V	
7	V _{DD}	Power	Positive supply voltage (3.0 V to 5.5 V)	
8	OE	(LV)CMOS/(LV)TTL Input	Output Enable for the clock outputs. Outputs are enabled when HIGH or when left open; OE pin has internal pull-up resistor. Three-states outputs when LOW.	

MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Units
V_{DD}	Positive Power Supply	GND = 0 V	-	7.0	V
V _I /V _O	Input/Output Voltage	t ≤ 1.5 ns	-	$\text{GND-1.5} \leq \text{V}_{\text{I}}/\text{V}_{\text{O}} \leq \text{V}_{\text{DD}}+1.5$	V
T _A	Operating Temperature Range, Industrial	-	-	≥ -40 to ≤ +85	°C
T _{stg}	Storage Temperature Range	-	-	-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 LFPM 500 LFPM	SOIC-8	190 130	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	(Note 1)	SOIC-8	41 to 44	°C/W
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 LFPM 500 LFPM	DFN-8 DFN-8	129 84	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. JEDEC standard multilayer board – 2S2P (2 signal, 2 power)

ATTRIBUTES

Characteristic		Value
ESD Protection	Human Body Model Machine Model	> 4 kV > 200 V
Moisture Sensitivity, Indefinite Ti	Level 1	
Flammability Rating Oxygen Index: 28 to 34		UL-94 code V-0 @ 0.125 in
Transistor Count	531 Devices	
Meets or Exceeds JEDEC Stand		

2. For additional Moisture Sensitivity information, refer to Application Note AND8003/D.

Symbol	Characteristic	Min	Тур	Max	Unit
I _{DD}	Power Supply Current @ 135 MHz, No Load, V_{DD} = 3.3 V	-	20	40	mA
V _{OH}	Output HIGH Voltage – I_{OH} = –25 mA, V_{DD} = 3.3 V	2.4	-	-	V
V _{OL}	Output LOW Voltage – I _{OL} = 25 mA	-	-	0.4	V
V _{OH}	Output HIGH Voltage – I _{OH} = –12 mA (CMOS level)	V _{DD} – 0.4	-	-	V
$V_{IH,} I_{CLK}$	Input HIGH Voltage, I _{CLK}	(V _{DD} /2)+0.7	-	3.8	V
$V_{IL,} I_{CLK}$	Input LOW Voltage, I _{CLK}	-	-	(V _{DD} /2)-0.7	V
$V_{\text{IH},}$ OE	Input HIGH Voltage, OE	2.0	-	VDD	V
V_{IL} OE	Input LOW Voltage, OE	0	-	0.8	V
ZO	Nominal Output Impedance	-	20	-	Ω
RPU	Input Pull-up Resistor, OE	-	220	-	kΩ
CIN	Input Capacitance, OE	-	5.0	_	pF
IOS	Short Circuit Current	-	± 50	_	mA

DC: CHARACTERISTICS (V_{O}) (High Ver 3.6 V, GND = 0 V, $T_{\Delta} = -40^{\circ}$ C to +85°C) (Note 3)

DC CHARACTERISTICS (V_{DD} = 4.5 V to 5.5 V, GND = 0 V, T_A = -40° C to $+85^{\circ}$ C) (Note 3)

Symbol	Characteristic	Min	Тур	Max	Unit
I _{DD}	Power Supply Current @ 135 MHz, No Load, V _{DD} = 5.0 V	-	50	95	mA
V _{OH}	Output HIGH Voltage – I _{OH} = –35 mA	2.4	-	-	V
V _{OL}	Output LOW Voltage – I _{OL} = 35 mA	-	-	0.4	V
V _{OH}	Output HIGH Voltage – I _{OH} = -12 mA (CMOS level)	$V_{DD} - 0.4$	-	-	V
V _{IH,} I _{CLK}	Input HIGH Voltage, I _{CLK}	(V _{DD} /2) + 1	-	5.5	V
V _{IL,} I _{CLK}	Input LOW Voltage, I _{CLK}	-	-	(V _{DD} /2) – 1	V
$V_{\text{IH},}$ OE	Input HIGH Voltage, OE	2.0	-	V _{DD}	V
V_{IL} OE	Input LOW Voltage, OE	0	-	0.8	V
ZO	Nominal Output Impedance	-	20	-	Ω
RPU	Input Pull-up Resistor, OE	-	220	-	kΩ
CIN	Input Capacitance, OE	-	5.0	-	pF
IOS	Short Circuit Current	-	±80	-	mA

AC CHARACTERISTICS (V_{DD} = 3.0 V to 5.5 V, GND = 0 V, T_A = -40° C to $+85^{\circ}$ C) (Note 3)

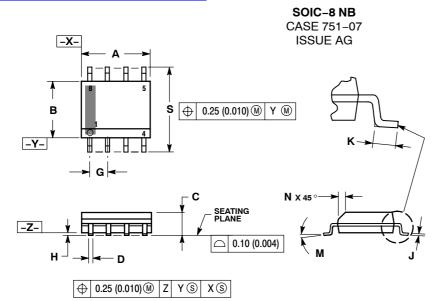
Symbol	Characteristic	Min	Тур	Мах	Unit
f _{in}	Input Frequency	-	-	180	MHz
t _{jitter (pd)}	Period Jitter (RMS, 1o)	-	2.0	-	ps
t _r /t _f	Output rise and fall times; 0.8 V to 2.0 V	-	0.5	1.0	ns
t _{pd}	Propagation Delay, CLK to Qn, 0 – 180 MHz, (Note 4)	1.5	3.0	6.0	ns
t _{skew}	Output-to-output skew; (Note 5)	-	50	160	ps

3. Outputs loaded with external $R_L = 33 - \Omega$ series resistor and $C_L = 15 \text{ pF}$ to GND for proper operation. Duty cycle out = duty in. A 0.01 μ F decoupling capacitor should be connected between V_{DD} and GND. A 33 Ω series terminating resistor may be used on each clock output if the trace is longer than 1 inch.

4. Measured with rail-to-rail input clock. 5. Measured on rising edges at $V_{DD} \div 2$.

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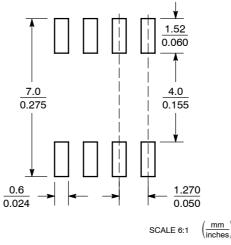
PACKAGE DIMENSIONS



- NOTES:
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
- MAXIMUM MATERIAL CONDITION. 6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

	MILLIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.80	5.00	0.189	0.197
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27	7 BSC	0.05	0 BSC
Н	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
к	0.40	1.27	0.016	0.050
М	0 °	8 °	0 °	8 °
Ν	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*

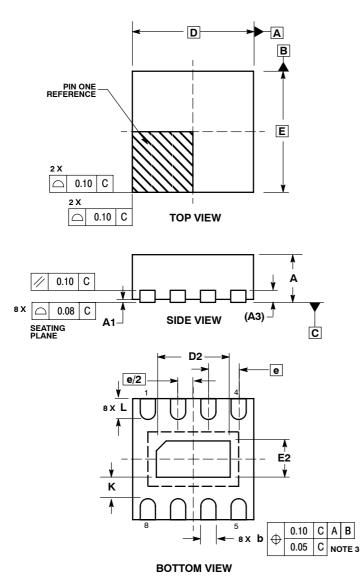


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PACKAGE DIMENSIONS

DFN8 CASE 506AA-01 ISSUE D



- NOTES: 1. DIMENSIONING AND TOLERANCING PER ASME X14 5M 1994
- ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: MILLIMETERS. 3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN
- 0.25 AND 0.30 MM FROM TERMINAL. 4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS		
DIM	MIN	MAX	
Α	0.80	1.00	
A1	0.00	0.05	
A3	0.20	REF	
b	0.20	0.30	
D	2.00	BSC	
D2	1.10	1.30	
E	2.00	BSC	
E2	0.70	0.90	
е	0.50 BSC		
К	0.20		
L	0.25	0.35	

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